



## Product Change Notification / MFOL-24ZYG1261

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### Date:

26-Apr-2024

### Product Category:

SAS Silicon & SW

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 6534 Final Notice: Qualification of HANK as an additional assembly site and WINS as an additional bumping site for PM8252B1-F3EIS1, PM8253B1-F3EIS1, PM8254B1-F3EIS1, PM8255B1-F3EIS1, PM8262B1-F3EIS1, PM8263B1-F3EIS1, PM8264B1-F3EIS1 and PM8265B1-F3EIS1 catalog part numbers (CPN) available in 884L BBGA (25x25x2.78mm) package.

### Affected CPNs:

[MFOL-24ZYG1261\\_Affected\\_CPN\\_04262024.pdf](#)

[MFOL-24ZYG1261\\_Affected\\_CPN\\_04262024.csv](#)

### Notification Text:

**PCN Status:**Final Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of HANK as an additional assembly site and WINS as an additional bumping site for PM8252B1-F3EIS1, PM8253B1-F3EIS1, PM8254B1-F3EIS1, PM8255B1-F3EIS1, PM8262B1-F3EIS1, PM8263B1-F3EIS1, PM8264B1-F3EIS1 and PM8265B1-F3EIS1 catalog part numbers (CPN) available in 884L BBGA (25x25x2.78mm) package.

### Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	Amkor Technology Korea (K4), INC  (ATK)	Amkor Technology Korea (K4), INC  (ATK)	Hana Micron Inc. (HANK)
Bumping Site	Taiwan Semiconductor Manufacturing Corp. (TSMC)	Taiwan Semiconductor Manufacturing Corp. (TSMC)	Winstek Semiconductor Technology Co.,Ltd. (WINS)
Substrate Core Material	E705G	E705G	E705G
SM Material	SR7300GR-B	SR7300GR-B	SR7300GR
Bump Material	Sn1.8Ag	Sn1.8Ag	Sn1.8Ag
Die Attach Epoxy	SCF-5	SCF-5	WF6317
Underfill Material	NAU-27-1F	NAU-27-1F	U8410-302LF1
Solder Ball Material	SAC305 ultra low $\alpha$	SAC305 ultra low $\alpha$	SAC305 ultra low $\alpha$
Solder Ball Flux	SCF-3	SCF-3	WF-6317

**Impacts to Data Sheet:**None

**Change Impact**None

**Reason for Change:**To improve productivity and on-time delivery performance by qualifying HANK as an additional assembly site and WINS as an additional bumping site.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**June 15, 2024 (date code: 2424)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	August 2023					>	April 2024					>	June 2024				
Workweek	31	32	33	34	35		14	15	16	17	18		23	24	25	26	27
Initial PCN Issue Date				x													
Qual Report Availability										x							

Final PCN Issue Date										X							
Estimated Implementation Date														X			

**Method to Identify Change:**Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**August 25, 2023: Issued initial notification.

April 26, 2024: Issued final notification. Attached the Qualification Report. Modified notification subject, description of change, qualification title, and purpose to include all affected part numbers. Provided estimated first ship date to be on June 15, 2024.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachments:

[PCN\\_MFOL-24ZYG1261\\_Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

## Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

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Affected Catalog Part Numbers (CPN)

- PM8252B1-F3EIS1
- PM8253B1-F3EIS1
- PM8254B1-F3EIS1
- PM8255B1-F3EIS1
- PM8262B1-F3EIS1
- PM8263B1-F3EIS1
- PM8264B1-F3EIS1
- PM8265B1-F3EIS1